



THE DATASHEET OF RS1MFSHMVG



1A, 200V - 1000V Surface Mount Fast Recovery Rectifier

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer, automotive and telecommunication

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.027 g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_{F(AV)}$	1	A
V_{RRM}	200 - 1000	V
I_{FSM}	30	A
$T_{J\ MAX}$	150	°C
Package	SOD-128	
Configuration	Single die	



SOD-128

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	RS1DFS	RS1GFS	RS1JFS	RS1KFS	RS1MFS	UNIT
Marking code on the device		RS1DFS	RS1GFS	RS1JFS	RS1KFS	RS1MFS	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V
Forward current	$I_{F(AV)}$	1					A
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	30					A
Junction temperature	T_J	- 55 to +150					°C
Storage temperature	T_{STG}	- 55 to +150					°C

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-lead thermal resistance per diode	$R_{\theta JL}$	29	$^{\circ}C/W$
Junction-to-ambient thermal resistance per diode	$R_{\theta JA}$	84	$^{\circ}C/W$
Junction-to-case thermal resistance per diode	$R_{\theta JC}$	30	$^{\circ}C/W$

Thermal Performance Note: Units mounted on recommended PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 0.5A, T_J = 25^{\circ}C$	V_F	0.94	1.10	V
	$I_F = 1.0A, T_J = 25^{\circ}C$		1.01	1.30	
	$I_F = 0.5A, T_J = 125^{\circ}C$		0.79	1.00	
	$I_F = 1.0A, T_J = 125^{\circ}C$		0.88	1.20	
Reverse current @ rated V_R per diode ⁽²⁾	$T_J = 25^{\circ}C$	I_R	-	5	μA
	$T_J = 125^{\circ}C$		-	50	μA
Junction capacitance	1 MHz, $V_R=4.0V$	C_J	7	-	pF
Reverse recovery time	$I_F=0.5A, I_R=1.0A$ $I_{RR}=0.25A$	t_{rr}	-	150	ns
			-	250	ns
			-	500	ns
			RS1DFS RS1GFS RS1JFS RS1KFS RS1MFS		

Notes:

1. Pulse test with PW=0.3 ms
2. Pulse test with PW=30 ms

ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX(*)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
RS1xFS (Note 1, 2)	H	MW	G	SOD-128	3,500 / 7" Plastic reel
		MX		SOD-128	14,000 / 13" Plastic reel

Notes:

1. "xx" defines voltage from 200V (RS1DFS) to 1000V (RS1MFS)
 2. Whole series with green compound (halogen-free)
- *: Optional available

EXAMPLE P/N					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
RS1DFSHMWG	RS1DFS	H	MW	G	AEC-Q101 qualified Green compound

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

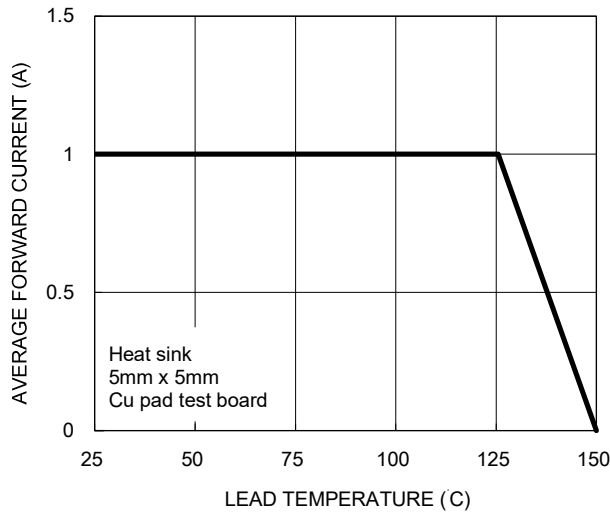


Fig.2 Typical Junction Capacitance

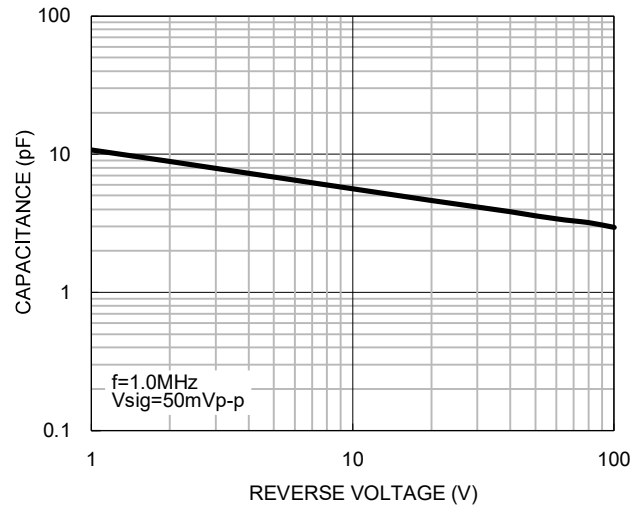


Fig.3 Typical Reverse Characteristics

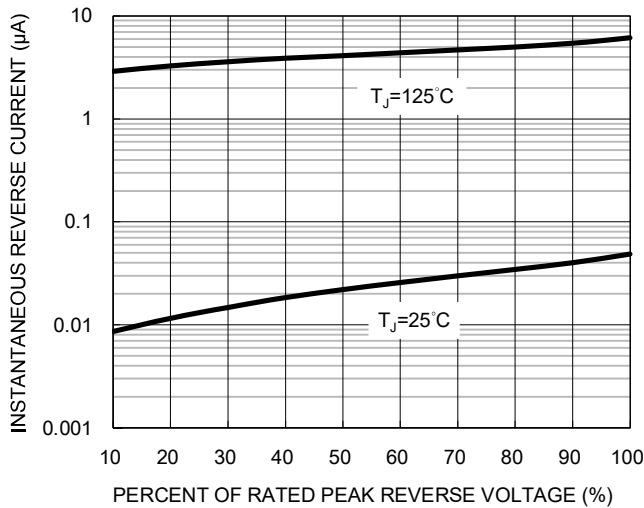
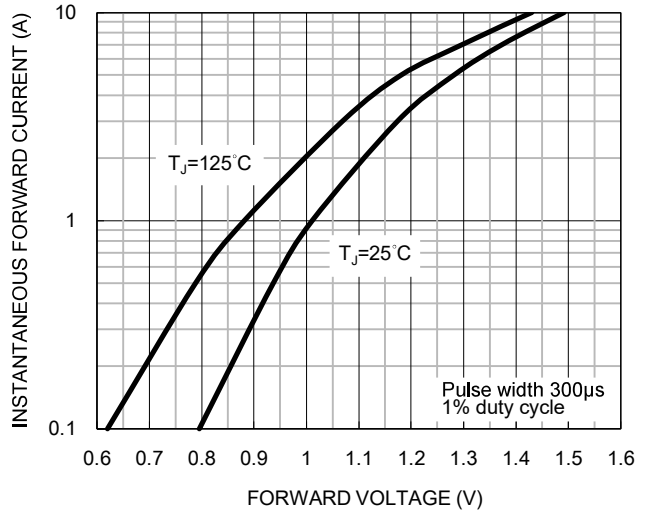
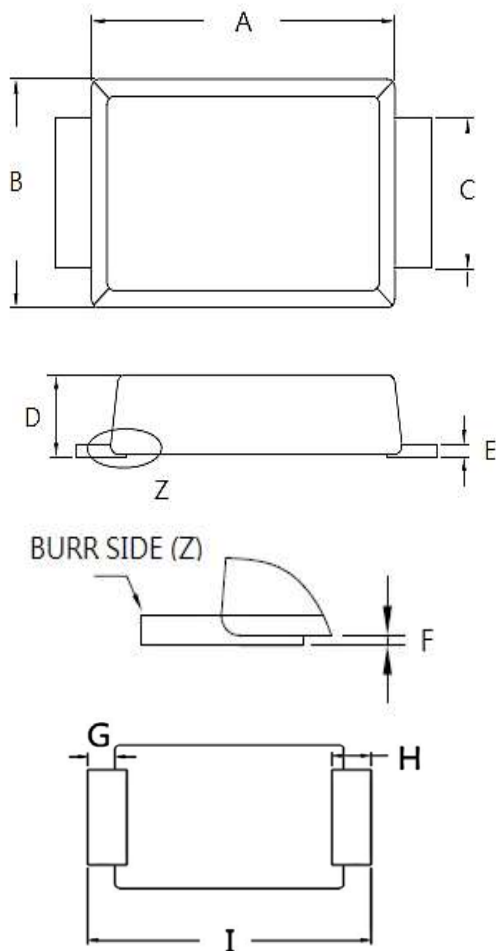


Fig.4 Typical Forward Characteristics



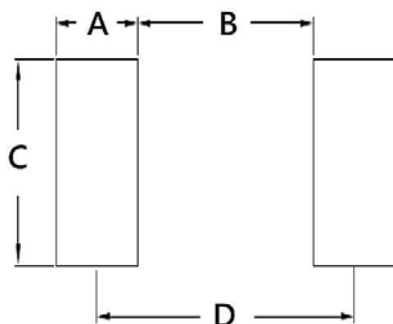
PACKAGE OUTLINE DIMENSIONS

SOD-128



DIM	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	3.60	4.00	0.142	0.157
B	2.30	2.70	0.091	0.106
C	1.60	1.90	0.063	0.075
D	0.90	1.10	0.035	0.043
E	0.10	0.22	0.004	0.009
F	0.00	0.10	0.000	0.004
G	0.30	0.60	0.012	0.024
H	0.40	0.80	0.016	0.031
I	4.40	5.00	0.173	0.197

SUGGESTED PAD LAYOUT



DIM	Unit (mm)	Unit (inch)
A	1.40	0.055
B	3.00	0.118
C	2.10	0.082
D	4.40	0.173

MARKING DIAGRAM



P/N = Marking Code
YW = Date Code
F = Factory Code

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View RS1MFSHMXG on WIN SOURCE](#)
- ⊖ [Taiwan Semiconductor Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management